

L Number	Hits	Search Text	DB	Time stamp
30	38	glass near (substrate or board) and (vias or (through near holes)) and filler and (display near device)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 56
31	52	361/760 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 56
32	26	361/748 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
33	15	361/750 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
34	13	361/751 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
35	16	361/761 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
36	8	361/765 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
37	19	361/767 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
38	7	361/768 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
39	10	361/772 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15: 57
40	0	roehling.in. and eves.in. and hewlett.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/20 15: 57
41	1	roehling.in. and eves.in.	EPO; JPO; DERWENT	2003/08/20 15: 57